

The GreenMOS<sup>®</sup> high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS<sup>®</sup> Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

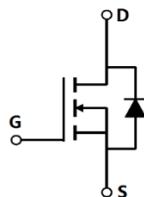
GreenMOS<sup>®</sup>



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Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	750	V
$I_{D, pulse}$	6	A
$R_{DS(ON), max} @ V_{GS}=10V$	2.6	
$Q_g$	7.9	nC

Product Name	Package	Marking
OSG70R2K6AF	TO251	OSG70R2K6A



**Absolute Maximum Ratings** at  $T_j=25$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	700	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25$ °C	$I_D$	2	A
Continuous drain current <sup>1)</sup> , $T_C=100$ °C		1.3	
Pulsed drain current <sup>2)</sup> , $T_C=25$ °C	$I_{D, pulse}$	6	A
Continuous diode forward current <sup>1)</sup> , $T_C=25$ °C	$I_S$	2	A
Diode pulsed current <sup>2)</sup> , $T_C=25$ °C	$I_{S, pulse}$	6	A
Power dissipation <sup>3)</sup> , $T_C=25$ °C	$P_D$	22.3	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	70	mJ
MOSFET dv/dt ruggedness, $V_{DS}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}$	dv/dt	15	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C

**Thermal Characteristics**

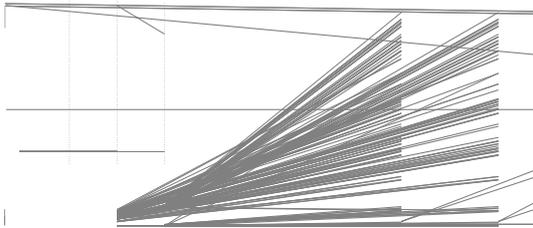
Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	5.6	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	R	62	°C/W

**Electrical Characteristics** at  $T_j=25$  unless otherwise specified

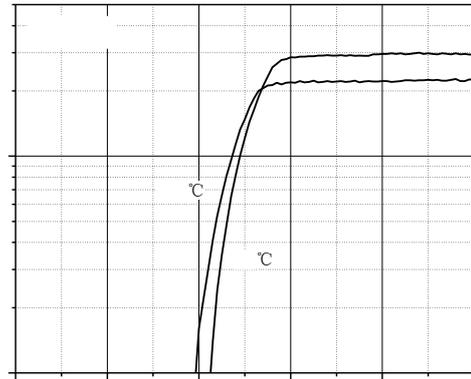
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	700			V	$V_{GS}=0$ V, $I_D=250$ A
		750	810			$V_{GS}=0$ V, $I_D$ , $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	2.0		4.0	V	$V_{DS}=V_{GS}$ , $I_D=250$ A
Drain-source on-state resistance	$R_{DS(ON)}$		2.3	2.6		$V_{GS}=10$ V, $I_D=1$ A
			5.3			$V_{GS}=10$ V, $I_D=1$ A, $T_j=150$ °C
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	$I_{DSS}$			1	A	$V_{DS}=700$ V, $V_{GS}=0$ V

**OSG70R2K6AF**   
Enhancement Mode N-Channel Power MOSFET

**Electrical Characteristics Diagrams**



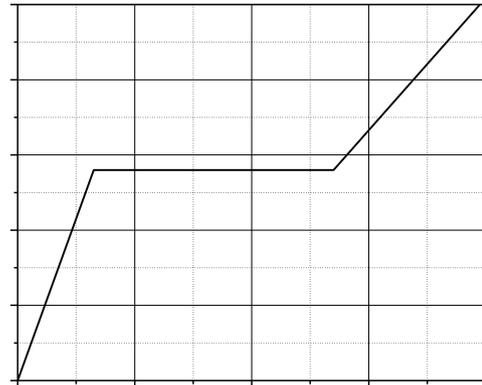
**Figure 1. Typ. output characteristics**



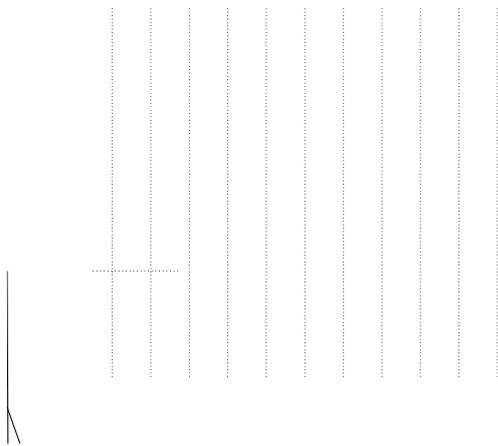
**Figure 2. Typ. transfer characteristics**



**Figure 3. Typ. capacitances**



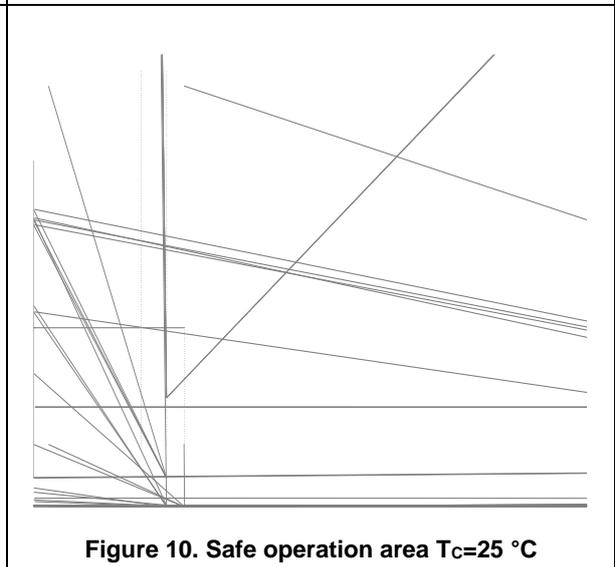
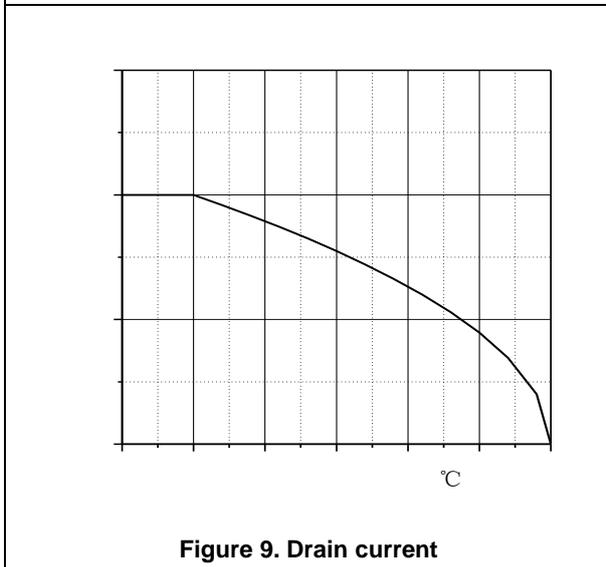
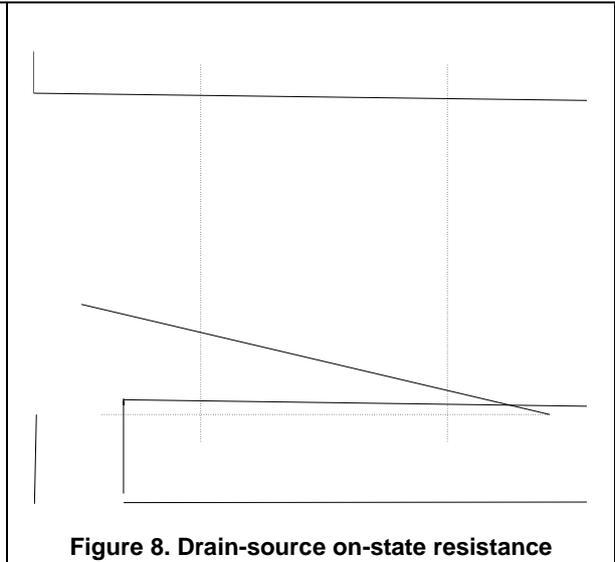
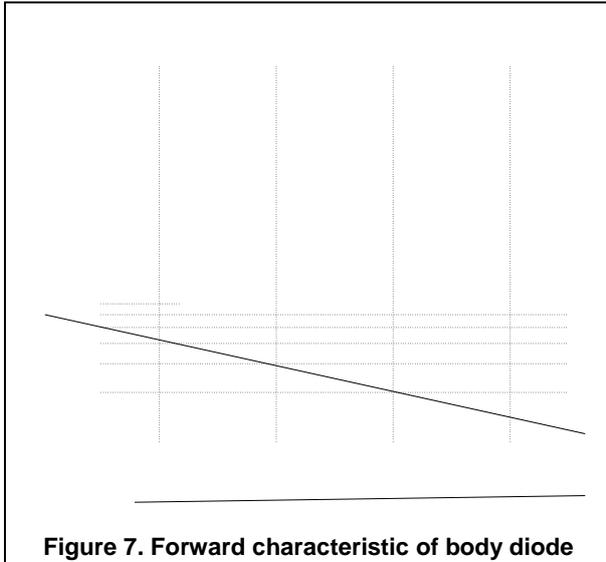
**Figure 4. Typ. gate charge**



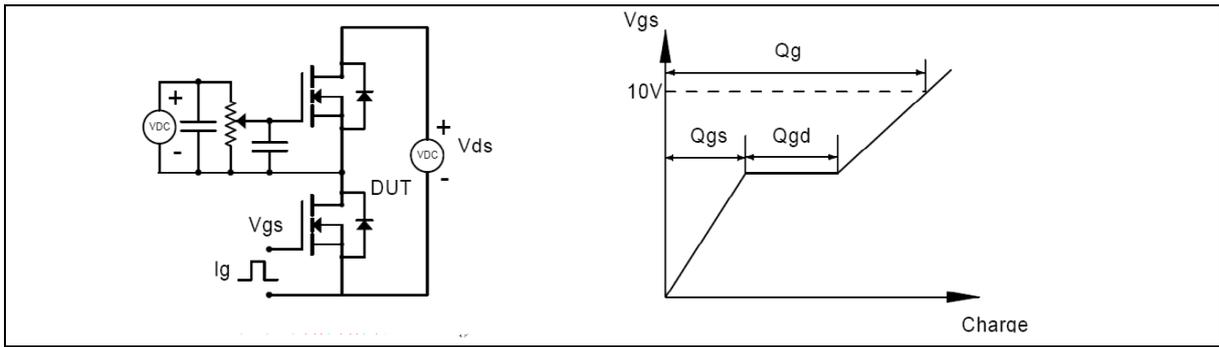
**Figure 5. Drain-source breakdown voltage**



**Figure 6. Drain-source on-state resistance**



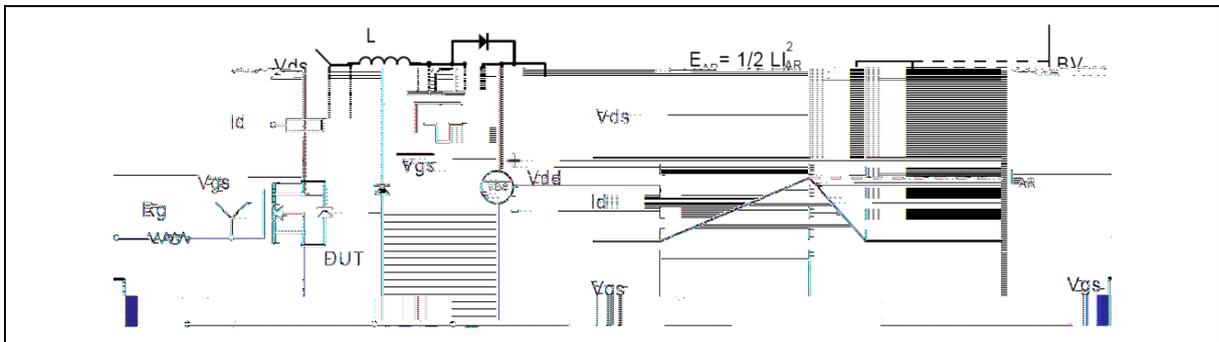
**Test circuits and waveforms**



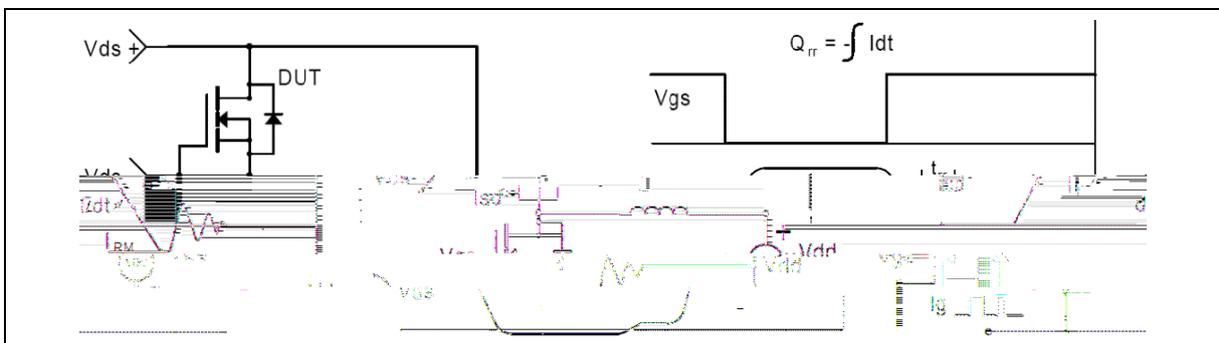
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**

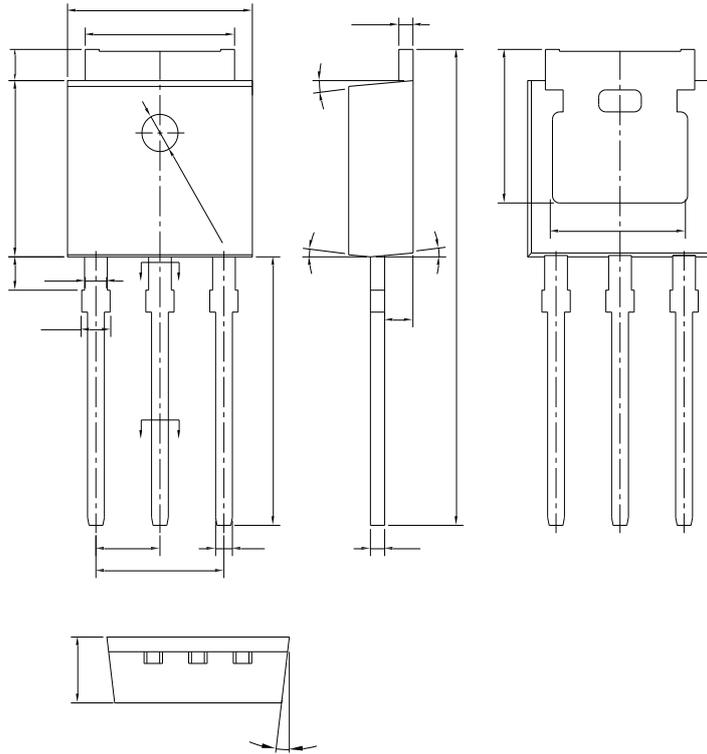


**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

**Package Information**



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.35
A1	0.90	1.01	1.10
b	0.56	-	0.69
b1	0.55	0.60	0.65
b2	0.77	-	0.90
b3	0.76	0.81	0.86
b4	5.23	5.33	5.43
b5	-	-	1.05
c	0.46	-	0.59
c1	0.45	0.51	0.55
c2	0.46	-	0.59
D	6.00	6.10	6.20
D1	5.20	-	-
E	6.50	6.60	6.70
E1	4.60	4.83	5.00
e	2.24	2.29	2.34
e1	4.47	4.57	4.67
H	16.18	16.48	16.78
L	9.00	9.30	9.60
L1	0.95	1.16	1.35
L2	0.90	1.08	1.25

Version 1: TO251-J package outline dimension

**Ordering Information**

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO251-J	75	60	4500	5	22500

**Product Information**

Product	Package	Pb Free	RoHS	Halogen Free
OSG70R2K6AF	TO251	yes	yes	yes

